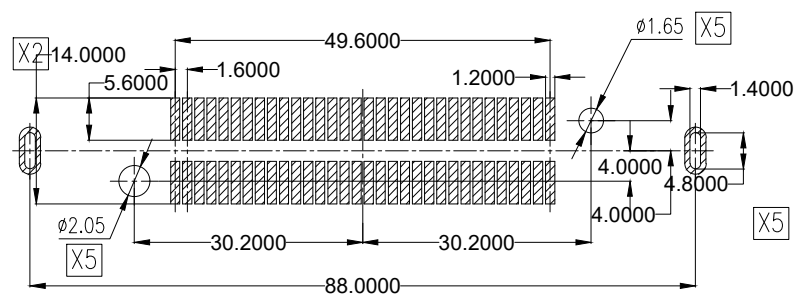
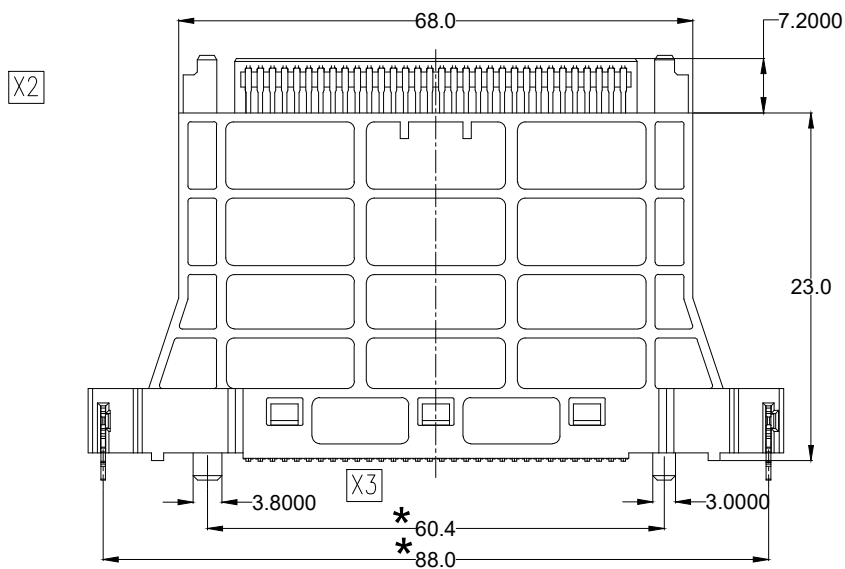
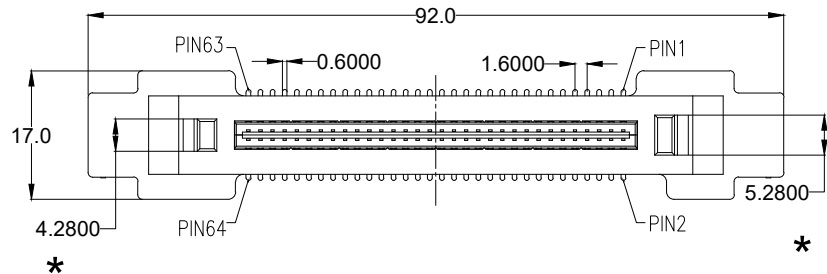
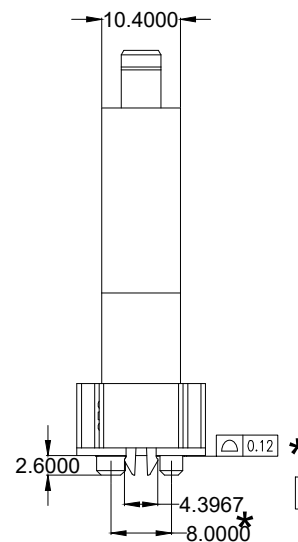


PROPRIETARY INFORMATION
COMPANY CONFIDENTIAL



RECOMMENDED PCB LAYOUT
TOLERANCE:±0.05mm

REV.	ECN. NO.	DESCRIPTION	ENG	DATE
X1		INITIAL	AXL	7/6/2016
X2		REVISE DWG	TERRY	7/7/2016
X3		REVISE DWG	JANE	8/6/2016
X4		ADD SPEC	Y'IN	9/18/2018
X5		REVISE PCB DIMENSION	Y'IN	5/17/2019
X6		ADD KEY DIMENSION NUMBERS	TERRY	8/14/2019
X7		CHANGED 5G TO 8G	ZAKK	6/19/2023



- NOTES :
1. MATERIAL
HOUSING: LCP, UL94V-0, BLACK
TERMINAL: BRASS
BOARDLOCK: BRASS
 2. PLATING:
TERMINAL:
CONTACT AREA: GOLD PLATING
SOLDER TAIL: 80u" TIN PLATING
UNDER PLATING: 30u" NICKEL OVERALL
BOARDLOCK: 80u" TIN PLATING; UNDER PLATING: 30u" NICKEL OVERALL.
 3. CURRENT RATING: 0.5A
 4. DIELECTRIC WITHSTANDING VOLTAGE: 500VAC FOR 1 MINUTE.
 5. INSULATION RESISTANCE: 100Mohms min.
 6. 8G GEN 3 PCIE min. COMPLIANT.
 7. DESIGN TO MATE WITH 110-10008.
 8. TRAY PACKAGING.
 9. MARK * IS KEY DIMENSION
 10. STACKING HEIGHT IS 28mm
- PART. NUMBER

110-10013-XX

01: GOLD FLASH PLATING
02: 30u" Au PLATING

GENERAL TOLERANCE X ± 0.50 .X ± 0.40 .XX ± 0.30 .XXX ± 0.20		ANGLE TOLERANCE X° ± 5.0° .X° ± 3.0° .XX° ± 2.0° .XXX° ± 1.0°		DRAWN JANE		DATE 8/6/16'			
MATL				CHECKED		DATE		TITLE HI-STACK B TO B 8Gbps MALE INTERFACE	
FINISH				APPROVED		DATE		PART NUMBER 110-10013-XX	
SCALE <i>N/A</i>		UNIT <i>mm</i>				DRAWING NO. 110-10013			SIZE <i>A4</i> REV. <i>1</i>
SHEET 1 OF 1									